System Configuration/Role of Each Line and Component

In semiconductor manufacturing processes, etching equipment, sputtering equipment, ion implantation equipment, and CVD equipment generally process wafers and LCD's in a vacuum chamber.

The peripheral equipment used to exhaust (vacuum) air from and supply atmospheric pressure to the vacuum chamber, such as valves, regulators, pressure switches, cylinders and gate valves should meet conditions such as nonleakage, clean specifications, and corrosion resistance.



The system consists of **a load lock chamber C** which introduces a wafer from the clean room into the chamber, **a transfer chamber B** which receives a wafer and moves it in and out, and **a process chamber A** in which the wafer is processed. Each chamber is exhausted with a vacuum pump in order to maintain a vacuum pressure.

Role of Each Line and Component

Exhaust lines

The exhaust line can be divided into the process chamber exhaust line ① and the transfer chamber and load-lock chamber exhaust line ②.

Exhaust line (1) has a high vacuum manual angle valve (XLH) between a dry vacuum pump and a turbo-molecular pump and a high vacuum angle valve (XLC) between a turbo-molecular pump and the process chamber.

When these valves are closed, vacuum is maintained in the process chamber and maintenance can be performed on the pumps.

Also, the process gas (reaction gas) can be introduced to the process chamber by closing the high pressure angular valve.

Exhaust line ② is used to evacuate the transfer chamber and the load-lock chamber. The load-lock chamber is restored to atmospheric pressure temporarily while a wafer is introduced. After introduction of the wafer, air is exhausted with a dry vacuum pump. When the pressure is reduced to a certain point, the turbo-molecular pump is used for exhaust. A by-pass circuit is provided with a high-vacuum smooth exhaust valve (XLD) and a high-vacuum angle valve (XLA/XLF).

The smooth vent valve XVD is used to supply air slowly at the initial stage after opening and, on achieving a certain pressure, to switch to the main valve for a full supply to prevent particle turbulence.

N₂ gas/air supply line (3)

When a wafer is introduced to the load-lock chamber C, the chamber has to temporarily restore atmospheric pressure. N_2 or clean air is supplied for this purpose. The gas introduced to the chamber must have a high degree of cleanliness.

For fluid contact parts, stainless steel fittings are generally used. Non-leakage specification VCR[®] or Swagelok fittings[®] are adopted wherever possible. The smooth vent valve XVD is used to change the flow rate of N₂ or clean air, which is supplied slowly at the initial stage after opening and, on achieving a certain pressure, is switched to the main valve for a full supply to prevent particle turbulence.

At the entrance of the chamber, the flow is rectified with a clean gas filter (with 100% filtration efficiency of 0.01 μ m particles) and a stainless steel diffusion element inside the chamber.

Cooling water/Temperature control line (4)(5)

In order to optimize wafer processing and deposit removal, the temperature in each chamber (especially the process chamber) is precisely controlled.

The cooling water line can be used with devices such as the 2 port solenoid valves for water (VDW/VX2), flow switch (PF3W), clean regulator (SRH), and pressure switch (ISE80).

Thermo-chillers and thermo-controllers are used to cool and maintain the chamber temperatures.

Slit valve/Transfer

In each chamber, vacuum and atmosphere are divided by a slit valve (XGT). Wafer transfer inside a chamber is enabled by the use of a vacuum cylinder (CYV).

Series Variations

Exhaust Line

Description	Model	Shaft seal system Valve type	Flange size	Material	Page	
Aluminum High Vacuum Angle Valve	XLA	Bellows seal	16, 25, 40, 50, 63, 80 (KF [NW]/K [DN] Note 1))		P.401	
 High fluorine resistance Minimal outgassing Minimal contamination from heavy metals 	XLA XLAV (With solenoid valves) XLC XLC (With solenoid valves)	Single acting (N.C.) Bellows seal	16, 25, 40, 50, 63 80, 100, 160 (KF [NW]/K [DN] ^{Note 1)})	Body: Aluminum alloy Bellows: Stainless steel 316L		
		Double acting	(KF [NW]/K [DN] ^{Note 1)})			
	XLF XLFV (With solenoid valves)	O-ring seal Single acting (N.C.)	16, 25, 40, 50, 63 80, 100, 160 (KF [NW]/K [DN] ^{Note 1)})	Body: Aluminum alloy Main part: Stainless steel, FKM ^{Note 3)}	P.413	
	XLG XLGV (With solenoid valves)	O-ring seal Double acting	16, 25, 40, 50, 63 80, 100 ^{Note 2)} , 160 ^{Note 2)} (KF [NW]/K [DN] ^{Note 1)})	Body: Aluminum alloy Main part: Stainless steel, FKM ^{Note 3)}		
	XLD XLDV (With solenoid valves)	Bellows/ O-ring seal 2-Step Control	25, 40, 50, 63, 80, 100, 160 (KF [NW]/K [DN] ^{Note 1)})	Body: Aluminum alloy		
	XLH	Manual	16, 25, 40, 50 (K [NW])	Bellows: Stainless steel 316L		
	XLS	Single acting (N.C.)	16, 25 (KF [NW])	Body: Aluminum alloy Main part: Stainless steel, PFA,FKM Note 3)		
Aluminum One-touch Connection and Release High Yacuum Angle Valve • One-touch connection and release (No tools are required.)	XLAQ	Bellows seal Single acting (N.C.)	16, 25, 40, 50 (KF [NW])	Body: Aluminum alloy	P.467	
	XLDQ	Bellows/ O-ring seal 2-Step Control	40, 50 (KF [NW])	Bellows: Stainless steel 316L		
Stainless Steel High Vacuum Angle Valve	ХМА	Bellows seal Single acting (N.C.)	16, 25, 40, 50, 63, 80		P.479	
 A precision casting, unified composition prevents accumulation of gas. The XM series is interchangeable with the XL series, aluminum high vacuum angle valve. 	ХМС	Bellows seal Double acting	(KF [NW]/K [DN] Note 1)/CFNote 4)			
	XMD	Bellows/ O-ring seal 2-Step Control	25, 40, 50, 63, 80 (KF [NW]/K [DN] ^{Note 1)} /CF ^{Note 4)})			
	хмн	Manual	16, 25, 40, 50 (KF [NW]/CF ^{Note 4)})	Body: SCS13 (equivalent to stainless steel 304)		
Stainless Steel High Vacuum In-line Valve	ХҮА	Bellows seal Single acting (N.C.)	25, 40, 50, 63, 80	Bellows: Stainless steel 316L		
• Combination with the angle valve allows space saving.	хүс	Bellows seal Double acting	(KF [NW]/K [DN] Note 1))			
	ХҮД	Bellows/ O-ring seal 2-Step Control	25, 40, 50, 63, 80 (KF [NW]/K [DN] ^{Note 1)})		P.479	
	хүн	Manual	25, 40, 50 (KF [NW])			

Note 3) Standard seal

Note 1) Applicable to flange sizes over 63. Note 2) Made to order. Solenoid valves are not available. Note 4) Only applicable to flange sizes 16, 40, and 63.



10

N2 Gas/Air Supply Line

Description	Model	Fitting size	Material	Page
Normal Close High Vacuum Solenoid Valve	XSA	Face seal fitting Compression fitting 1/4, 3/8		P.511
Smooth Vent Valve • Valve / needle valve integrated construction – requires only 1/4 the piping space of previous models. • Particulates significantly reduced through the use of a metal diaphragm in the sheet portion • Row of both initial air supply and main air supply can be adjusted. XVD		1/4 (For VCR®/Swagelok®)	Body: Stainless steel Main part: Stainless steel, FKM (seal material)	P.522

Slit Valve

Description	Model	Opening window size Height x width (mm)	Applicable wafer size	Number of axis	Material	Page
Slit Valve • This product is suitable for the partition valve between the load lock chamber and the transfer chamber or between the transfer chamber and the process cham- ber in semiconductor equipment	XGT22	32 x 222	200 mm	Two axes bellows	Body: A5052 Gate: A6063 Bellows: AM350 Seal Material: FKM, Kalrez 4079	P.527
or other equipment.		46 x 236				
	XGT31	50 x 336	300 mm	One axis bellows		

Transfer Line

Description	Model	Bore size (mm)	Port size	Material	Page	XG
Rodless Cylinder for Vacuum • Air cylinder for transfer in vacuum environments (1.3 x 10 ⁴ Pa)		15	5/16-24UNF	Body: Aluminum allow	D 525	CYV
	CYV	32	7/16-20UNF	Linear: Stainless steel O-ring: Fluororubber	1.000	

⊘SMC

XLA XLQ XLQ D-Q XSA XVD XGT